Film Capacitors

Metallized Polypropylene Film Capacitors (MFP)

Series/Type: **B32686A**

Date: December 2012

EPCOS AG is a TDK Group Company.

Typical applications
- Smoothing
- Snubbering
- High-frequency AC loads

Climatic
- Max. operating temperature: 110 °C
- Climatic category (IEC 60068-1): 55/100/56

Construction
- Dielectric: polypropylene (PP)
- Film metallized on one side and metal foils internally connected in series
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

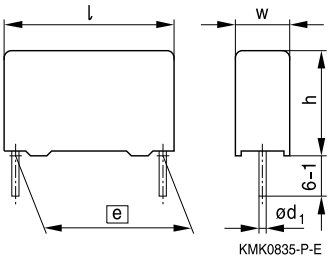
Features
- Very high pulse strength
- Highest possible contact reliability
- Self-healing properties
- RoHS-compatible

Terminals
- Parallel wire leads, lead-free tinned
- Special lead lengths available on request

Marking
Manufacturer's logo,
series number,
style (MFP),
rated capacitance,
capacitance tolerance (code letter),
rated DC voltage,
date of manufacture (coded)

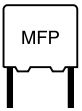
Delivery mode
Bulk (untaped)

Dimensional drawing



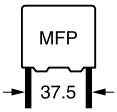
Dimensions in mm

Lead spacing e ±0.4	Lead diameter d_1	Type
37.5	1.0	B32686A



Overview of available types

Lead spacing	37.5 mm			
Type	B32686A			
V_R (V DC)	1000	1250	1600	2000
V_{RMS} (V AC)	400	450	450	500
C_R (nF)				
22				
33				
47				
68				
100				
150				
220				
330				
470				



B32686A

Very high pulse (wound)

Ordering codes and packing units (lead spacing 37.5 mm)

V_R	V_{RMS} f ≤1 kHz	C_R	Max. dimensions w × h × l	Ordering code (composition see	Untaped
V DC	V AC	nF	mm	below)	pcs./MOQ
1000	400	68	12.0 × 22.5 × 42.0	B32686A0683+000	288
		100	12.0 × 22.5 × 42.0	B32686A0104+000	288
		150	14.0 × 25.0 × 42.0	B32686A0154+000	224
		220	16.0 × 28.5 × 42.0	B32686A0224+000	192
		330	20.0 × 39.5 × 42.0	B32686A0334+000	128
		470	20.0 × 39.5 × 42.0	B32686A0474+000	128
1250	450	68	12.0 × 22.5 × 42.0	B32686A7683+000	288
		100	14.0 × 25.0 × 42.0	B32686A7104+000	224
		150	16.0 × 28.5 × 42.0	B32686A7154+000	192
		220	18.0 × 32.5 × 42.0	B32686A7224+000	192
		330	20.0 × 39.5 × 42.0	B32686A7334+000	128
1600	450	47	12.0 × 22.5 × 42.0	B32686A1473+000	288
		68	14.0 × 25.0 × 42.0	B32686A1683+000	224
		100	18.0 × 32.5 × 42.0	B32686A1104+000	192
		150	20.0 × 39.5 × 42.0	B32686A1154+000	128
2000	500	22	12.0 × 22.5 × 42.0	B32686A2223+000	288
		33	14.0 × 25.0 × 42.0	B32686A2333+000	224
		47	16.0 × 28.5 × 42.0	B32686A2473+000	192
		68	18.0 × 32.5 × 42.0	B32686A2683+000	192
		100	20.0 × 39.5 × 42.0	B32686A2104+000	128

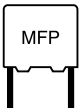
MOQ = Minimum Order Quantity, consisting of 4 packing units.
Further E series and intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:
K = ±10%
J = ±5%

Technical data

Operating temperature range	Max. operating temperature $T_{op,max}$		+110 °C
	Upper category temperature T_{max}		+100 °C
	Lower category temperature T_{min}		−55 °C
	Rated temperature T_R		+85 °C
Dissipation factor tan δ (in 10^{-3})	at	$C_R \leq 0.1$ µF	$C_R > 0.1$ µF
at 20 °C	1 kHz	−	0.4
(upper limit values)	10 kHz	0.4	0.5
	100 kHz	1.0	−
Insulation resistance R_{ins}	$C_R \leq 0.33$ µF	$C_R > 0.33$ µF	
or time constant $\tau = C_R \cdot R_{ins}$	100 GΩ	30 000 s	
at 20 °C, rel. humidity ≤ 65%			
(minimum as-delivered values)			
DC test voltage	$2.0 \cdot V_R$, 2 s		
Category voltage V_C	T_A (°C)	DC voltage derating	AC voltage derating
(continuous operation with V_{DC}	$T_A \leq 85$	$V_C = V_R$	$V_{C,RMS} = V_{RMS}$
or V_{AC} at f ≤ 1 kHz)	$85 < T_A \leq 100$	$V_C = V_R \cdot (165 - T_A)/80$	$V_{C,RMS} = V_{RMS} \cdot (165 - T_A)/80$
Operating voltage V_{op}	T_A (°C)	DC voltage (max. hours)	AC voltage (max. hours)
for short operating periods	$T_A \leq 85$	$V_{op} = 1.25 \cdot V_C$ (2000 h)	$V_{op} = 1.0 \cdot V_{C,RMS}$ (2000 h)
V_{DC} or V_{AC} at f ≤ 1 kHz)	$85 < T_A \leq 100$	$V_{op} = 1.25 \cdot V_C$ (1000 h)	$V_{op} = 1.0 \cdot V_{C,RMS}$ (1000 h)
Damp heat test	56 days/40 °C/93% relative humidity		
Limit values after damp	Capacitance change $\lvert\Delta C/C\rvert$		≤ 2%
heat test	Dissipation factor change Δ tan δ		≤ $1.0 \cdot 10^{-3}$ (at 10 kHz)
	Insulation resistance R_{ins}		≥ 50% of minimum
	or time constant $\tau = C_R \cdot R_{ins}$		as-delivered values
Reliability:			
Failure rate λ	1 fit (≤ $1 \cdot 10^{-9}$/h) at $0.5 \cdot V_R$, 40 °C		
Service life t_{SL}	200 000 h at $1.0 \cdot V_R$, 85 °C		
	For conversion to other operating conditions and temperatures, refer to chapter "Quality, 2 Reliability".		
Failure criteria:			
Total failure	Short circuit or open circuit		
Failure due to variation	Capacitance change $\lvert\Delta C/C\rvert$		> 10%
of parameters	Dissipation factor tan δ		4 · upper limit value
	Insulation resistance R_{ins}		< 1500 MΩ ($C_R \leq 0.33$ µF)
	or time constant $\tau = C_R \cdot R_{ins}$		< 500 s ($C_R > 0.33$ µF)



B32686A

Very high pulse (wound)

Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in V/µs.

"k_0" represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in $V^2/\mu s$.

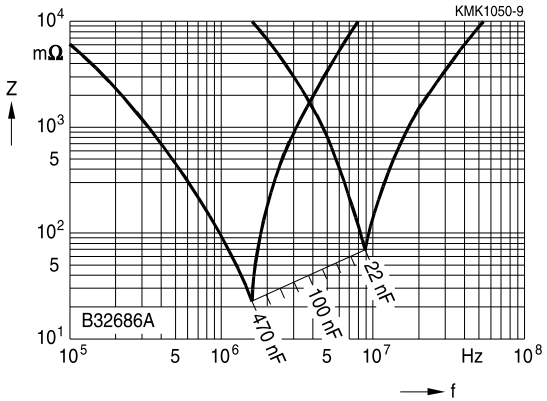
Note:
The values of dV/dt and k_0 provided below must not be exceeded in order to avoid damaging the capacitor.

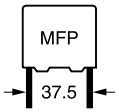
dV/dt and k_0 values

Lead spacing		37.5 mm	
V_R (V DC)	V_{RMS} (V AC)	dV/dt in V/µs	k_0 in $V^2/\mu s$
1000	400	2 000	4 000 000
1250	450	2 800	7 000 000
1600	450	3 500	11 000 000
2000	500	4 500	18 000 000

Impedance Z versus frequency f

(typical values)

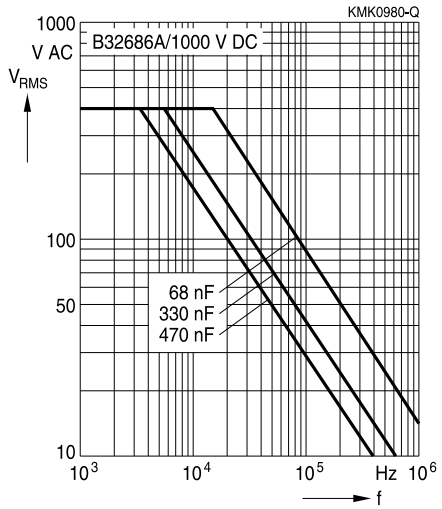




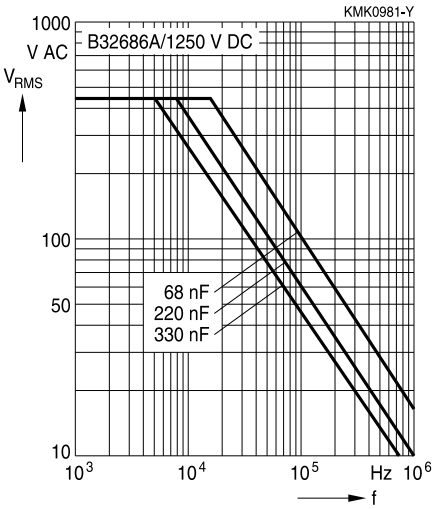
Permissible AC voltage V_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 90$ °C)
For T_A >90 °C, please refer to "General technical information", section 3.2.3.

Lead spacing 37.5 mm

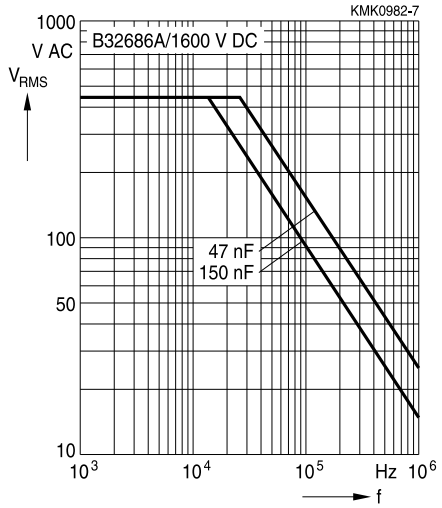
1000 V DC/400 V AC



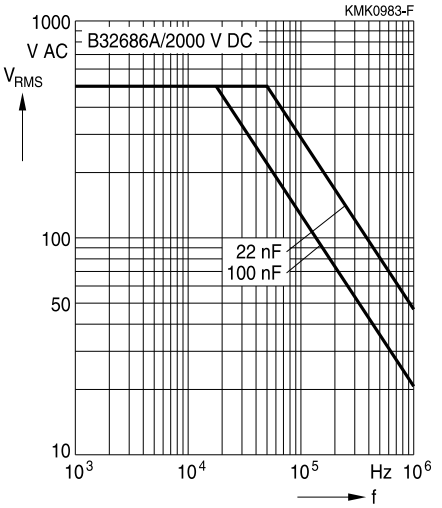
1250 V DC/450 V AC



1600 V DC/450 V AC



2000 V DC/500 V AC



Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

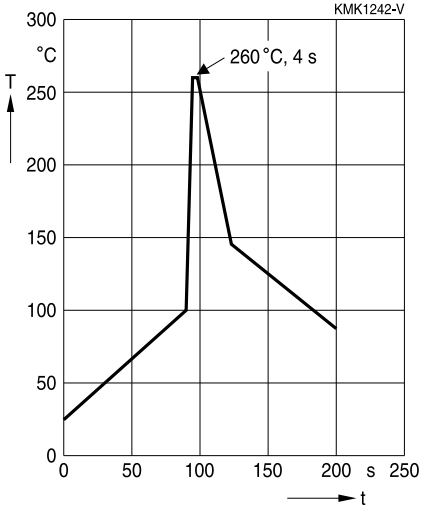
Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Evaluation criteria: Visual inspection	 Wetting of wire surface by new solder ≥90%, free-flowing solder

1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A.
Conditions:

Series		Solder bath temperature	Soldering time
MKT	boxed (except 2.5 × 6.5 × 7.2 mm) coated uncoated (lead spacing > 10 mm)	260 ±5 °C	10 ±1 s
MFP MKP	 (lead spacing > 7.5 mm)		
MKT	boxed (case 2.5 × 6.5 × 7.2 mm)		5 ±1 s
MKP MKT	(lead spacing ≤ 7.5 mm) uncoated (lead spacing ≤ 10 mm) insulated (B32559)		< 4 s recommended soldering profile for MKT uncoated (lead spacing ≤ 10 mm) and insulated (B32559)



Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
tan δ	As specified in sectional specification

1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max}. Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
  diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
  - MKP/MFP 110 °C
  - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

Uncoated capacitors

For uncoated MKT capacitors with lead spacings ≤10 mm (B32560/B32561) the following measures are recommended:

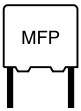
- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering

Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"



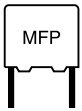
B32686A

Very high pulse (wound)

Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_C	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
β_C	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
C	Capacitance	Kapazität
C_R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
$\Delta \tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f_1	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
f_2	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
f_r	Resonant frequency	Resonanzfrequenz
F_D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F_T	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I_C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)



B32686A

Very high pulse (wound)

Symbol	English	German
I_{RMS}	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
i_z	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impulskennwert
L_S	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λ_0	Constant failure rate during useful service life	Konstante Ausfallrate in der Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des Entladekreises
R_i	Internal resistance	Innenwiderstand
R_{ins}	Insulation resistance	Isolationswiderstand
R_P	Parallel resistance	Parallelwiderstand
R_S	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
T	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
tan δ_D	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ_P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ_S	Series component of dissipation factor	Serienanteil des Verlustfaktors
T_A	Ambient temperature	Umgebungstemperatur
T_{max}	Upper category temperature	Obere Kategorietemperatur
T_{min}	Lower category temperature	Untere Kategorietemperatur
t_{OL}	Operating life at operating temperature and voltage	Betriebszeit bei Betriebstemperatur und -spannung
T_{op}	Operating temperature	Beriebstemperatur
T_R	Rated temperature	Nenntemperatur
T_{ref}	Reference temperature	Referenztemperatur
t_{SL}	Reference service life	Referenz-Lebensdauer
V_{AC}	AC voltage	Wechselspannung

Symbol	English	German
V_C	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige) Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_i	Input voltage	Eingangsspannung
V_o	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V_R	Rated voltage	Nennspannung
$\hat{v}_R$	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
Z	Impedance	Scheinwiderstand
e	Lead spacing	Rastermaß

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or lifesaving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
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